

PESD5V0X1UALD

Ultra low capacitance unidirectional ESD protection diode

Rev. 1 — 5 April 2011

Product data sheet

1. Product profile

1.1 General description

Ultra low capacitance unidirectional ElectroStatic Discharge (ESD) protection diode designed to protect one signal line from the damage caused by ESD and other transients. The device is housed in a SOD882D leadless ultra small Surface-Mounted Device (SMD) plastic package with visible and solderable side pads.

1.2 Features and benefits

- ESD protection of one line
- Ultra low diode capacitance
 $C_d = 1.55$ pF
- Ultra small SMD plastic package
- Solderable side pads
- Package height typ. 0.37 mm
- Ultra low leakage current: $I_{RM} = 1$ nA
- ESD protection up to 15 kV
- IEC 61000-4-2; level 4 (ESD)
- Low clamping voltage: $V_{CL} = 9$ V
- IEC 61000-4-5 (surge); $I_{PP} = 2$ A
- AEC-Q101 qualified

1.3 Applications

- Computers and peripherals
- Audio and video equipment
- Cellular handsets and accessories
- 10/100/1000 Mbit/s Ethernet
- Communication systems
- Portable electronics
- Subscriber Identity Module (SIM) card protection
- USB, High-Definition Multimedia Interface (HDMI), FireWire
- High-speed data lines

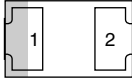
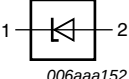
1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{RWM}	reverse standoff voltage		-	-	5.5	V
C_d	diode capacitance	$f = 1$ MHz; $V_R = 0$ V	-	1.55	1.75	pF



2. Pinning information

Table 2. Pinning			
Pin	Description	Simplified outline	Graphic symbol
1	cathode		
2	anode		

[1] The marking bar indicates the cathode.

3. Ordering information

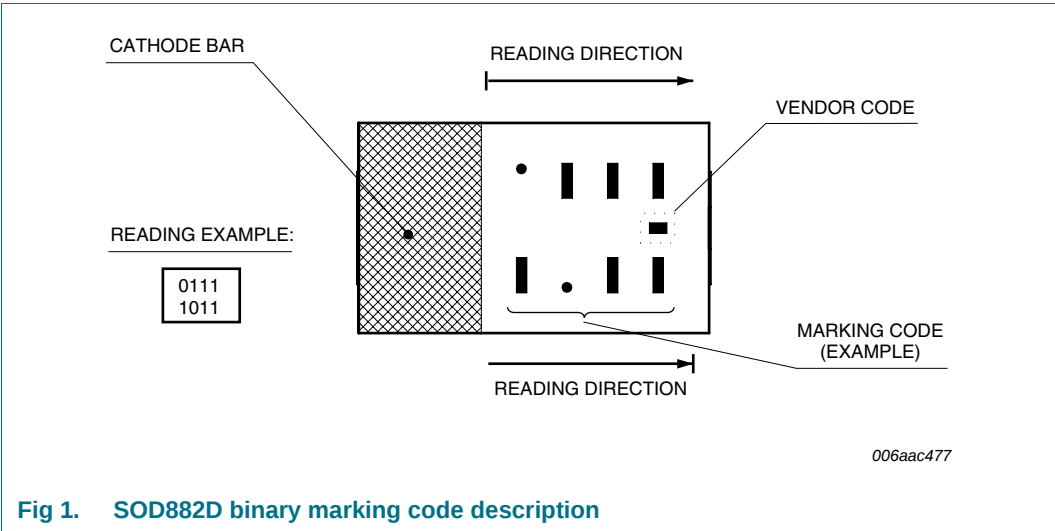
Table 3. Ordering information			
Type number	Package		
	Name	Description	Version
PESD5V0X1UALD	-	leadless ultra small plastic package; 2 terminals; body 1 × 0.6 × 0.4 mm	SOD882D

4. Marking

Table 4. Marking codes	
Type number	Marking code[1]
PESD5V0X1UALD	0000 1000

[1] For SOD882D binary marking code description, see [Figure 1](#).

4.1 Binary marking code description



5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
I_{PP}	peak pulse current	$t_p = 8/20 \mu s$	[1][2] -	2	A
T_j	junction temperature		-	150	°C
T_{amb}	ambient temperature		-55	+150	°C
T_{stg}	storage temperature		-65	+150	°C

[1] Non-repetitive current pulse 8/20 μs exponential decay waveform according to IEC 61000-4-5.

[2] Measured from pin 1 to 2.

Table 6. ESD maximum ratings

$T_{amb} = 25^\circ C$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Max	Unit
V_{ESD}	electrostatic discharge voltage	IEC 61000-4-2 (contact discharge)	[1][2] -	15	kV
		machine model	-	400	V
		MIL-STD-883 (human body model)	[2] -	10	kV

[1] Device stressed with ten non-repetitive ESD pulses.

[2] Measured from pin 1 to 2.

Table 7. ESD standards compliance

Standard	Conditions
IEC 61000-4-2; level 4 (ESD)	> 15 kV (air); > 8 kV (contact)
MIL-STD-883; class 3 (human body model)	> 4 kV

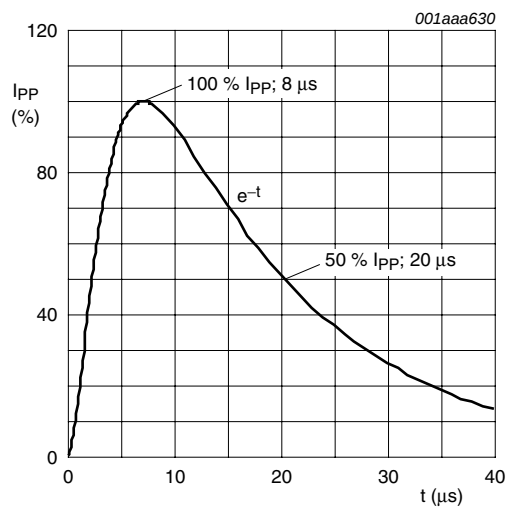


Fig 2. 8/20 μs pulse waveform according to IEC 61000-4-5

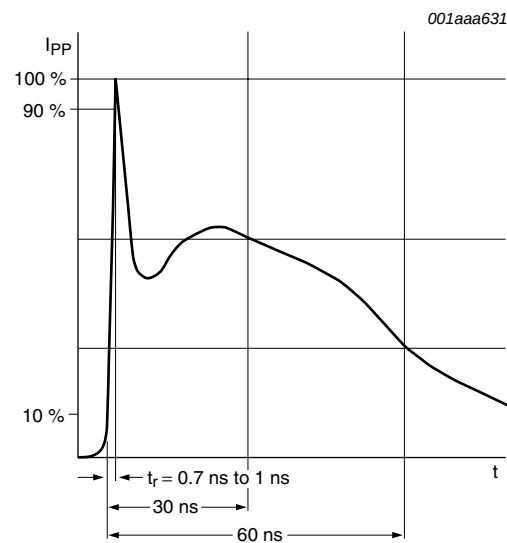


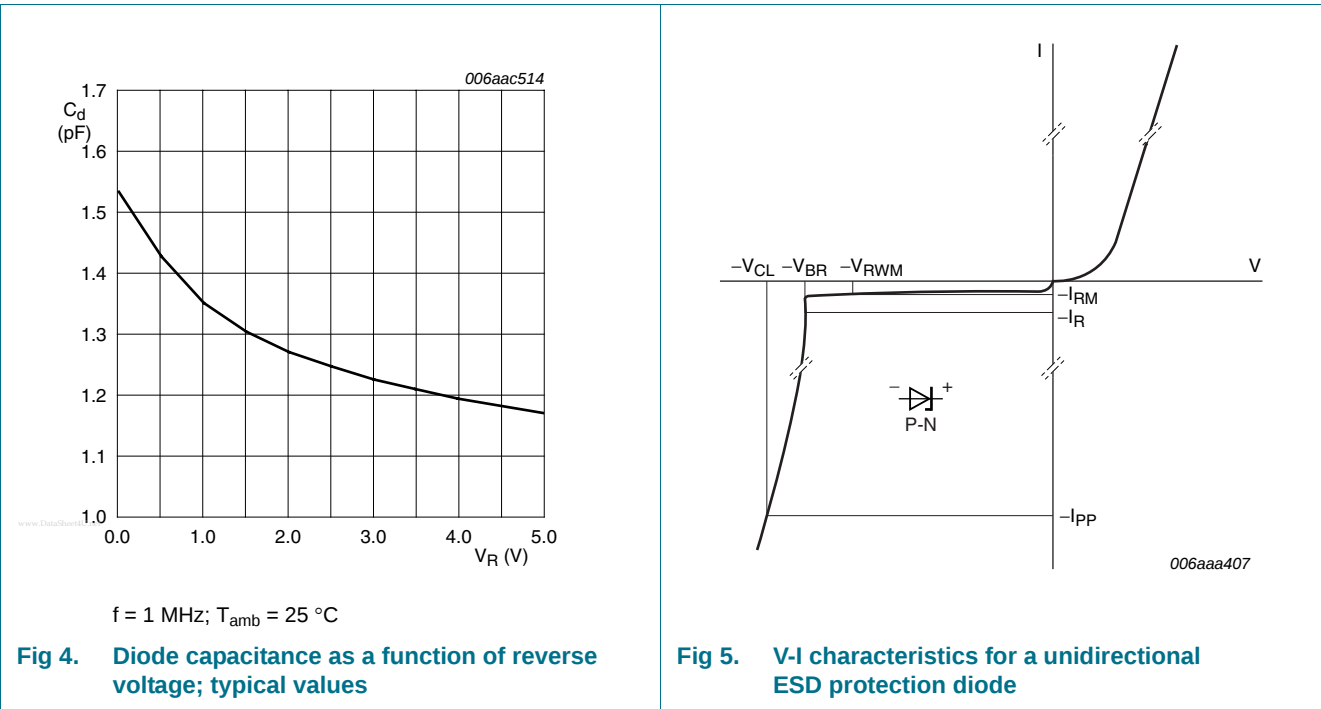
Fig 3. ESD pulse waveform according to IEC 61000-4-2

6. Characteristics

Table 8. Characteristics
T_{amb} = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{RWM}	reverse standoff voltage		-	-	5.5	V
I _{RM}	reverse leakage current	V _{RWM} = 5.5 V	-	1	100	nA
V _{BR}	breakdown voltage	I _R = 10 mA	5.8	7.5	10	V
C _d	diode capacitance	f = 1 MHz; V _R = 0 V	-	1.55	1.75	pF
V _{CL}	clamping voltage	I _{PP} = 2 A	[1][2]	-	9	V
r _{dyn}	dynamic resistance	I _R = 10 A	[3]	0.15	-	Ω

- [1] Non-repetitive current pulse 8/20 μs exponential decay waveform according to IEC 61000-4-5.
[2] Measured from pin 1 to 2.
[3] Non-repetitive current pulse, Transmission Line Pulse (TLP) t_p = 100 ns; square pulse; ANS/IESD STM5-1-2008.



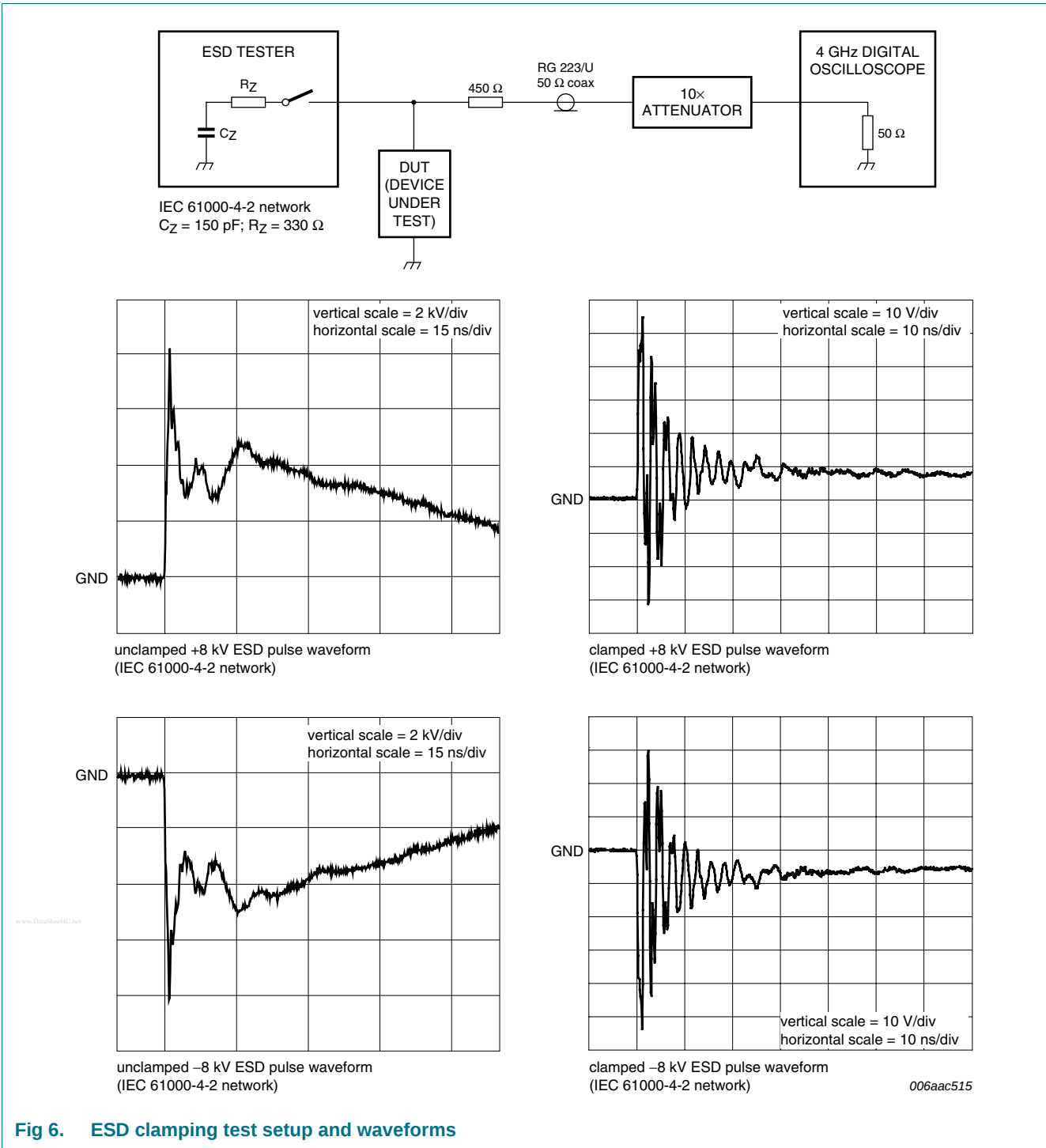


Fig 6. ESD clamping test setup and waveforms

7. Application information

The PESD5V0X1UALD is designed for the protection of one unidirectional data or signal line from the damage caused by ESD and surge pulses. The device may be used on lines where the signal polarities are either positive or negative with respect to ground.

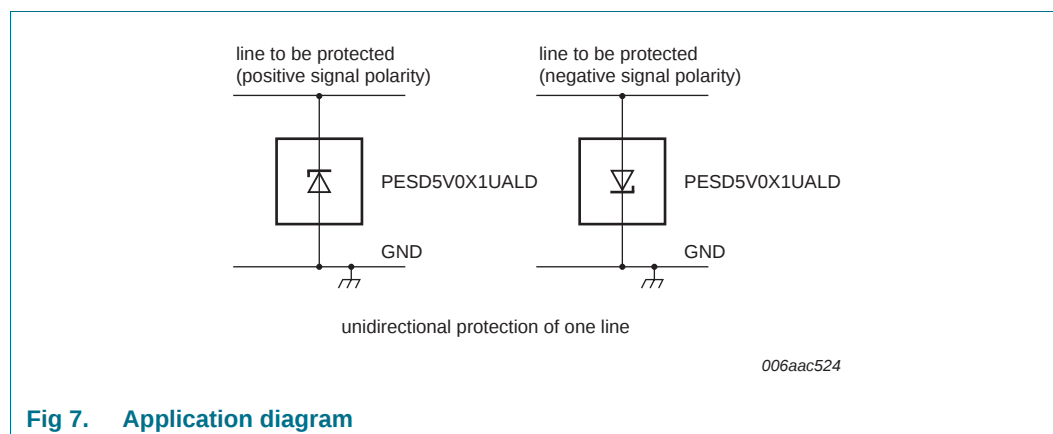


Fig 7. Application diagram

Circuit board layout and protection device placement

Circuit board layout is critical for the suppression of ESD, Electrical Fast Transient (EFT) and surge transients. The following guidelines are recommended:

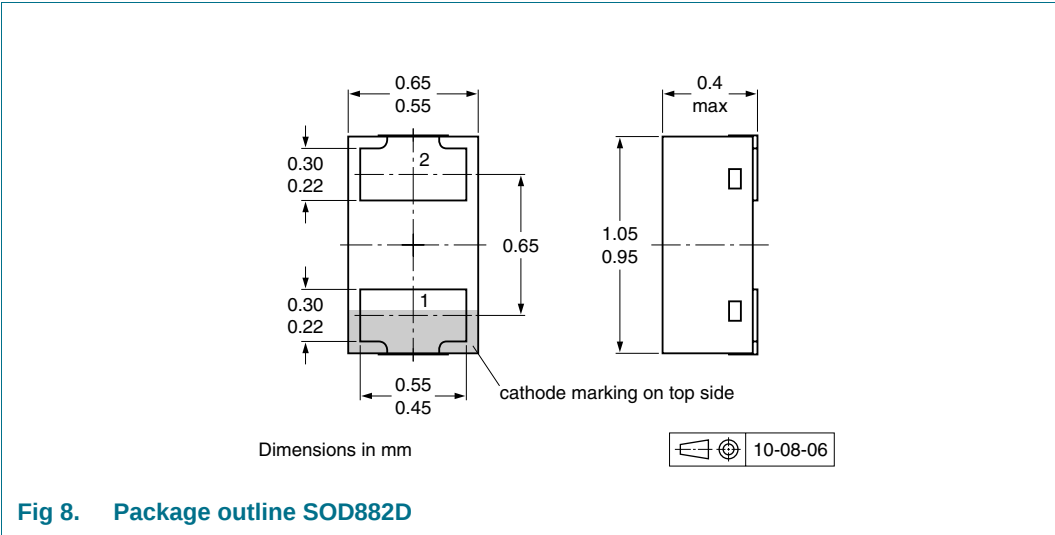
1. Place the PESD5V0X1UALD as close to the input terminal or connector as possible.
2. The path length between the PESD5V0X1UALD and the protected line should be minimized.
3. Keep parallel signal paths to a minimum.
4. Avoid running protected conductors in parallel with unprotected conductors.
5. Minimize all Printed-Circuit Board (PCB) conductive loops including power and ground loops.
6. Minimize the length of the transient return path to ground.
7. Avoid using shared transient return paths to a common ground point.
8. Ground planes should be used whenever possible. For multilayer PCBs, use ground vias.

8. Test information

8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

9. Package outline



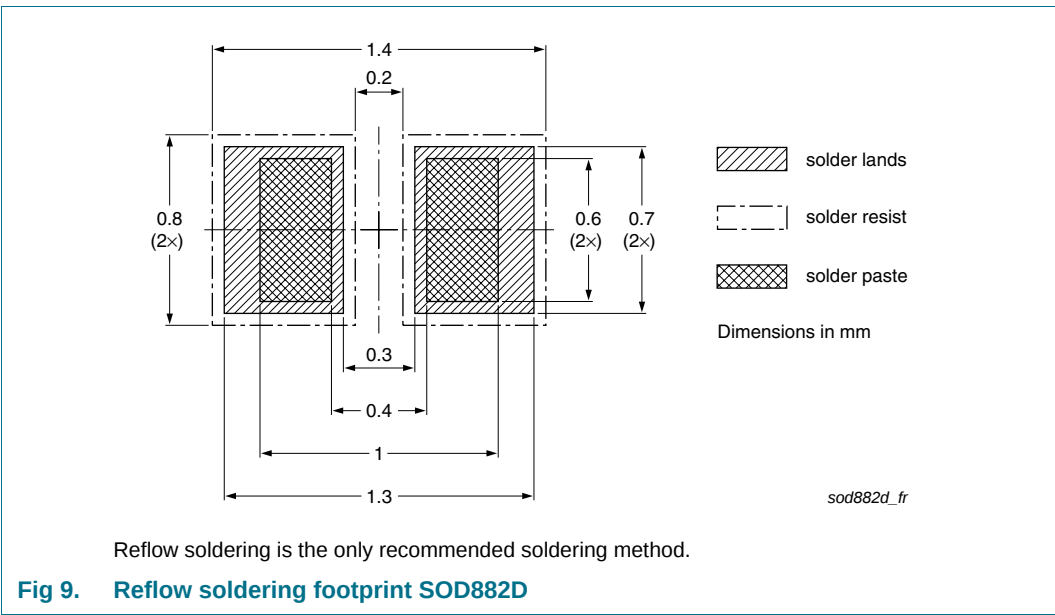
10. Packing information

Table 9. Packing methods
The indicated -xxx are the last three digits of the 12NC ordering code.[\[1\]](#)

Type number	Package	Description	Packing quantity
			10000
PESD5V0X1UALD	SOD882D	2 mm pitch, 8 mm tape and reel	-315

[1] For further information and the availability of packing methods, see [Section 14](#).

11. Soldering



12. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PESD5V0X1UALD v.1	20110405	Product data sheet	-	-

13. Legal information

13.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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